



PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Toshinori NAKAYAMA

Group Art Unit: 2811

Application No.: 09/626,146

Examiner: O. Nadav

Filed: July 26, 2000

Docket No.: 106364

10/a
FJONES
3-19-02

For: SUBSTRATE FOR SEMICONDUCTOR DEVICE, SEMICONDUCTOR CHIP MOUNTING SUBSTRATE, SEMICONDUCTOR DEVICE AND METHOD OF FABRICATION THEREOF, AND CIRCUIT BOARD, TOGETHER WITH ELECTRONIC EQUIPMENT

AMENDMENT UNDER 37 C.F.R. §1.111

Director of the U.S. Patent and Trademark Office
Washington, D.C. 20231

Sir:

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In reply to the Office Action dated November 1, 2001, the period for reply being extended by the attached Petition for Extension of Time, please amend the above-identified application as follows:

IN THE CLAIMS:

✓
Please cancel claims 1-14 and 22-28 without prejudice or disclaimer. Applicant reserves the right to file one or more divisional applications drawn to these claims.

Please replace claims 15-19 as follows:

- Sub C17
15. (Amended) A semiconductor device comprising:
- a semiconductor chip;
 - a substrate on which the semiconductor chip is mounted and which is formed by cutting apart a larger substrate; and
 - resin for sealing the semiconductor chip;
 - wherein the semiconductor device has side surfaces, each of the side surfaces are flat, each of the side surfaces are made of at least an edge surface of the substrate and an